b) replacing at least a portion of the ceramic material with a microporous dielectric material, wherein the microporous dielectric material is at least partially disposed between and contacts the first conductive sheets and the second conductive sheets.

5. The method of claim **4**, wherein step b) comprises:

etching away at least a portion of the ceramic material; and

applying the microporous dielectric material to replace at least a portion of the ceramic material removed by etching.

6. The method of claim **4**, wherein substantially all of the ceramic material is replaced with the microporous dielectric material.

7. The method of claim **6**, wherein step b) comprises:

etching away substantially all of the ceramic material; and

applying the microporous dielectric material to replace of the ceramic material removed by etching.

8. The method of claim **4**, wherein the microporous dielectric material comprises a polymer of intrinsic microporosity.

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